TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

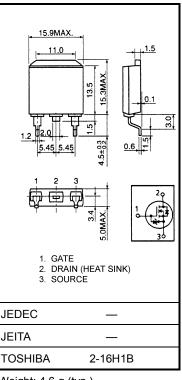
2SK3117

Chopper Regulator DC–DC Converter and Motor Drive Applications

- Low drain-source ON resistance $R_{DS}(ON) = 0.21 \Omega$ (typ.)
- High forward transfer admittance $|Y_{fs}| = 17 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DSS} = 500 \ V)$
- Enhancement mode $: V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ID} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	500	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V _{DGR}	500	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	20	А	
	Pulse (Note 1)	I _{DP}	80	А	
Drain power dissipation (Tc = 25° C)		PD	150	W	
Single pulse avalanche energy (Note 2)		E _{AS}	960	mJ	
Avalanche current		I _{AR}	20	А	
Repetitive avalanche energy (Note 3)		E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	50	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 4.08 mH, R_G = 25 Ω , I_{AR} = 20 A

Note 3: Repetitive rating pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm

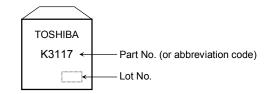
Electrical Characteristics (Ta = 25°C)

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V		—	±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_		V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V		_	100	μA
Drain-source br voltage	eakdown	V _(BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500	_	_	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 10 A	_	0.21	0.27	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 10 A	10	17	_	S
Input capacitance	e	C _{iss}		—	3720	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	—	340	_	pF
Output capacitance		Coss			1165		
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \prod_{\substack{OV\\ GS}} \stackrel{I_{D}=10A}{}_{OVOUT}$		30	-	
	Turn-on time	t _{on}		_	70	_	-
	Fall time	t _f		_	50	_	ns
	Turn-off time	t _{off}	$v_{DD} = 200v$ Duty $\leq 1\%$, $t_w = 10\mu s$	_	290	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	80	—	
Gate-source charge		Q _{gs}	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 6 A		48	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	32	_	

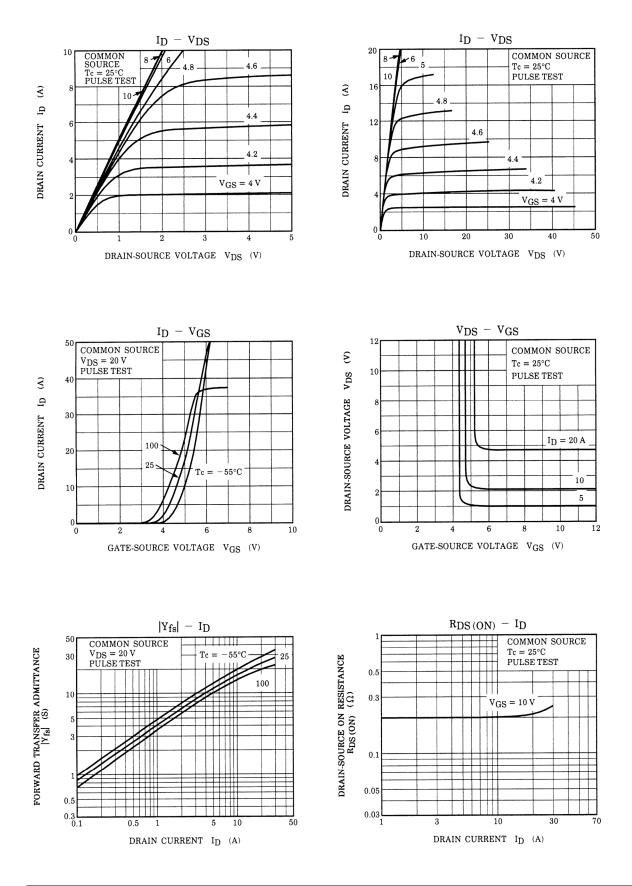
Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	20	А
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	80	А
Forward voltage (diode)	VDSF	V _{DR} = 20 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 20 A, V _{GS} = 0 V		540	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 100 A / µs	_	5.4	_	μC

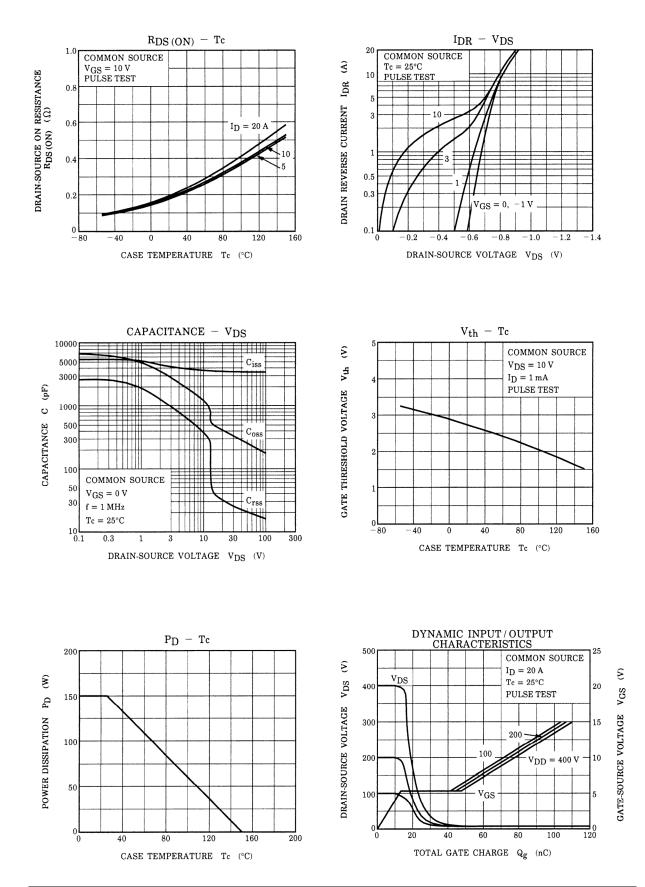
Marking

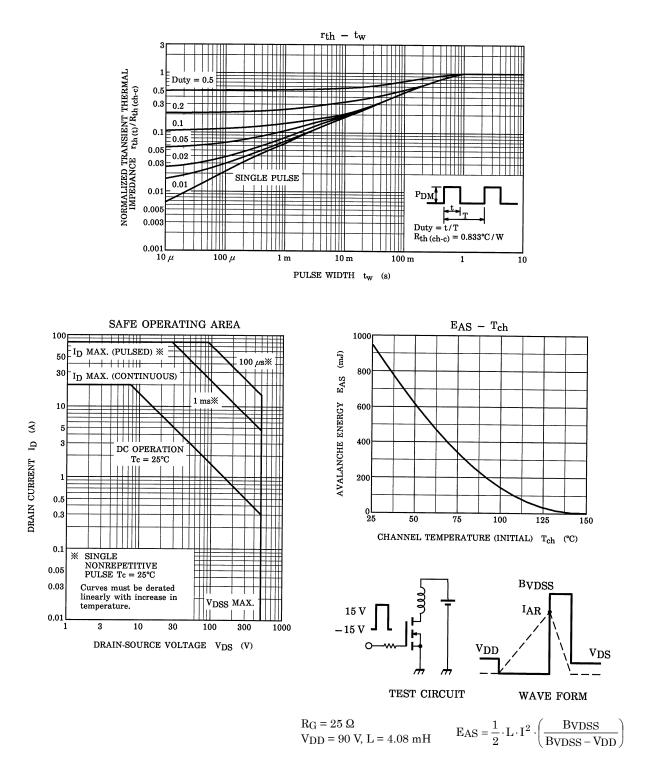


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